Statement of Compliance

Requested Part

21 April 2015 | **917249-1** | (Part 1 of 1)

DYNAMIC D-3400F REC HSG 20P

Part Status:	Active
Mil-Spec Certified:	No
EU RoHS/ELV Code:	Always EU RoHS/ELV Compliant
Solder Process Capability Code:	Not applicable for solder process capability
China RoHS:	No Restricted Materials Above Threshold
Exemptions:	None
REACH Oct 2008 SvHC Compliance:	Contains no REACH October 2008 SvHC(s)
REACH Jan/Mar 2010 SvHC Compliance:	Contains no REACH Jan/Mar 2010 SvHC(s)
REACH June 2010 SvHC Compliance:	Contains no REACH June 2010 SvHC(s)
REACH December 2010 SvHC Compliance:	Contains no REACH December 2010 SvHC(s)
REACH June 2011 SvHC Compliance:	Contains no REACH June 2011 SvHC(s)
REACH December 2011 SvHC Compliance:	Contains no REACH December 2011 SvHC(s)
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REACH June 2013 SvHC Compliance:	Contains no REACH June 2013 SvHC(s)
REACH December 2013 SvHC Compliance:	Contains no REACH December 2013 SvHC(s)
REACH June 2014 SvHC Compliance:	Contains no REACH June 2014 SvHC(s)
REACH December 2014 SvHC Compliance:	Contains no REACH December 2014 SvHC(s)
Halogen Content:	Not Low Halogen - contains Br or Cl > 900 ppm.

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hex chrome, mercury, PBB, PBDE, and 0.01% for cadmium, or qualify for an exemption to above limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Note that any exemptions taken in this case would not include application specific exemptions (e.g. lead in solder for servers) as TE cannot determine where component products will be used.

Additionally, the part numbers that are as 5 of 6 compliant meet the material limits described above, except that these products have lead in the solderable interface only. These products may be suitable for use in an application that has an exemption for the use of lead in solder (e.g. servers, network infrastructure, etc).

Finished electrical and electronic products will be CE marked as required by Directive 2011/65/EU (RoHS2). Components may not be CE marked.

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information provided by our suppliers. This information is subject to change.

Guy Degrieck

Manager, Product Environmental Compliance

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